

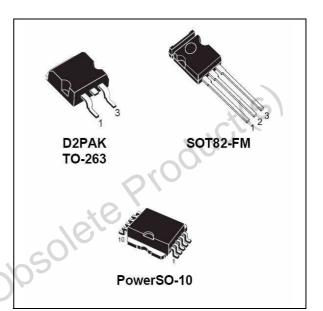
VNB14N04 - VNK14N04FM VNV14N04

"OMNIFET" fully autoprotected Power MOSFET

Features

Туре	V _{clamp}	R _{DS(on)}	l _{lim}
VNB14N04	42 V	0.07 Ω	14 A
VNK14N04FM	42 V	0.07 Ω	14 A
VNV14N04	42 V	0.07 Ω	14 A

- Linear current limitation
- Thermal shutdown
- Short circuit protection
- Integrated clamp
- Low current drawn from input pin
- Diagnostic feedback through input pin
- ESD protection
- Direct access to the gate of the power MOSFET (analog driving)
- Compatible with standard power MOSFET



Description

The VNB14N04, VNK14N04FM and VNV14N04 are monolithic devices made using STMicroeletronics VIPower M0 Technology, intended for replacement of standard power MOSFETS in DC to 50 kHz applications. Built-in thermal shutdown, linear current limitation and overvoltage clamp protect the chip in harsh environment.

Fault feedback can be detected by monitoring the voltage at the input pin.

Table 1. Device summary

Part number	Order code
VNB14N04	VNB14N04, VNB14N04-E, VNB14N0413TR, VNB14N04TR-E
VNK14N04FM	VNK14N04FM
VNV14N04	VNV14N04, VNV14N04-E

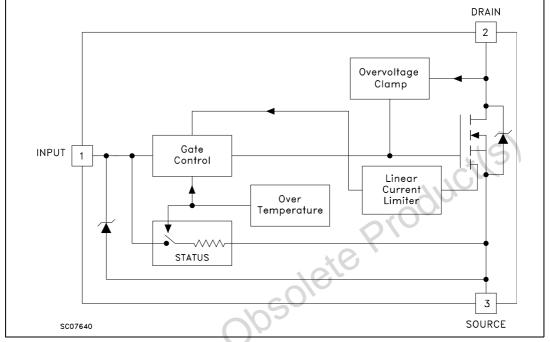
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1 Block diagram





1. PowerSO-10 pin configuration : INPUT = 6,7,8,9,10; SOURCE = 1,2,4,5; DRAIN = TAB

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2 Electrical specification

2.1 Absolute maximum rating

		Valu			
Symbol	Parameter	PowerSO-10 D2PAK	SOT-82FM	Unit	
Vds	Drain-source voltage (V _{in} = 0) Internally clamped			V	
Vin	Input voltage	18	18		
lD	Drain current	Internally	limited	A	
IR	Reverse DC output current	-14	-14 2000 50 9.5		
Vesd	Electrostatic discharge (C = 100 pF, R=1.5 K Ω)	200			
Ptot	Total dissipation at $T_c = 25 $ °C	50			
Tj	Operating junction temperature	Internally limited		C	
Τc	Case operating temperature	perating temperature Internally limited		C	
Tstg	Storage temperature	-55 to	C		

2.2 Thermal data

Table 3. Thermal data

	Symbol	Symbol Parameter		SOT82-FM	D2PAK	Unit
	Rthj-case	Thermal resistance junction-case max	2.5	13	2.5	℃/W
10	Rthj-amb	Thermal resistance junction-ambient max	50	100	62.5	°C/W

2.3

Electrical characteristics

 T_{case} =25 °C unless otherwise specified.

Table 4. Electrical characteristics

Symbol Parameter		Test conditions	Min.	Тур.	Max.	Unit
Off						
V _{CLAMP}	Drain-source clamp voltage	I _D = 200 mA V _{in} = 0	36	42	48	V
V _{CLTH}	Drain-source clamp threshold voltage	$I_D = 2 \text{ mA } V_{\text{in}} = 0$	35			V
V _{INCL}	Input-source reverse clamp voltage	I _{in} = -1 mA	-1		-0.3	V



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Symbol	Falameter		IVIIII.	тур.		
I _{DSS}	Zero input voltage drain current (V _{in} = 0)	$V_{DS} = 13 V V_{in} = 0$ $V_{DS} = 25 V V_{in} = 0$			50 200	μΑ μΑ
I _{ISS}	Supply current from input pin	V _{DS} = 0 V V _{in} = 10 V		250	500	μΑ
On ⁽¹⁾						
V _{IN(th)}	Input threshold voltage	$V_{DS} = V_{in} I_D + I_{in} = 1 \text{ mA}$	0.8		3	V
R _{DS(on)}	Static drain-source on resistance	V _{in} = 10 V I _D = 7 A V _{in} = 5 V I _D = 7 A			0.7 0.1	Ω Ω
Dynamic					ic	
g_{fs} ⁽¹⁾	Forward transconductance	V _{DS} = 13 V I _D = 7 A	8	10		S
C _{oss}	Output capacitance	V _{DS} = 13 V f = 1 MHz V _{in} = 0	2	400	500	pF
Switchir	ng ⁽²⁾		00			<u> </u>
t _{d(on)} t _r t _{d(off)} t _f	Turn-on delay time Rise time Turn-off delay time Fall time	$V_{DD} = 15 \text{ V I}_{d} = 7 \text{ A}$ $V_{gen} = 10 \text{ V R}_{gen} = 10 \Omega$ (see <i>Figure 26</i>)		60 160 250 100	120 300 400 200	ns ns ns ns
t _{d(on)} t _r t _{d(off)} t _f	Turn-on delay time Rise time Turn-off delay time Fall time	V_{DD} = 15 V I _d = 7 A V_{gen} = 10 V R _{gen} = 1000 Ω (see <i>Figure 26</i>)		300 1.5 5.5 1.8	500 2.2 7.5 2.5	ns µs µs µs
(di/dt) _{on}	Turn-on current slope	V _{DD} = 15 V I _D = 7 A V _{in} = 10 V R _{gen} = 10 Ω		120		A/µs
Qi	Total input charge	V _{DD} = 12 V I _D = 7 A V _{in} = 10 V		30		nC
Source drain diode						
V _{SD} ⁽¹⁾	Forward on voltage	I _{SD} = 7 A V _{in} = 0			1.6	V
t _{rr} ⁽²⁾ Q _{rr} ⁽²⁾ I _{RRM} ⁽²⁾	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 7 \text{ A di/dt} = 100 \text{ A/µs}$ $V_{DD} = 30 \text{ V T}_j = 25 \text{ °C}$ (see test circuit, <i>Figure 28</i>)		110 0.34 6.1		ns μC Α
Protecti	on					
I _{lim}	Drain current limit	$V_{in} = 10 V V_{DS} = 13 V$ $V_{in} = 5 V V_{DS} = 13 V$	10 10	14 14	20 20	A A
t _{dlim} (2)	Step response Current limit	V _{in} = 10 V V _{in} = 5 V		30 80	60 150	μs μs
T _{jsh} ⁽²⁾	Overtemperature shutdown		150			C
T _{jrs} ⁽²⁾	Overtemperature reset		135			°C

1able 4. Lieuliuai unai auteristius (uoritinueu)	Table 4.	Electrical characteristics	(continued)
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Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
$I_{gf}^{(2)}$	Fault sink current	$V_{in} = 10 V V_{DS} = 13 V$ $V_{in} = 5 V V_{DS} = 13 V$		50 20		mA mA
$E_{as}^{(2)}$	Single pulse avalanche energy	starting $T_j = 25 \text{ CV}_{DD} = 20 \text{ V}$ $V_{in} = 10 \text{ VR}_{gen} = 1 \text{ K}\Omega \text{ L} = 10 \text{ mH}$	0.65			J

Table 4. Electrical characteristics (continued)

1. Pulsed: Pulse duration = 300 $\mu s,$ duty cycle 1.5 %

2. Parameters guaranteed by design/characterization

3 Protection features

During normal operation, the Input pin is electrically connected to the gate of the internal power MOSFET. The device then behaves like a standard power MOSFET and can be used as a switch from DC to 50 kHz. The only difference from the user's standpoint is that a small DC current (liss) flows into the Input pin in order to supply the internal circuitry.

The device integrates:

- Overvoltage clamp protection: internally set at 42 V, along with the rugged avalanche characteristics of the Power MOSFET stage give this device unrivalled ruggedness and energy handling capability. This feature is mainly important when driving inductive loads.
- Linear current limiter circuit: limits the drain current Id to Ilim whatever the Input pin voltage. When the current limiter is active, the device operates in the linear region, so power dissipation may exceed the capability of the heatsink. Both case and junction temperatures increase, and if this phase lasts long enough, junction temperature may reach the overtemperature threshold T_{jsh}.
- Overtemperature and short circuit protection: these are based on sensing the chip temperature and are not dependent on the input voltage. The location of the sensing element on the chip in the power stage area ensures fast, accurate detection of the junction temperature. Overtemperature cutout occurs at minimum 150 °C. The device is automatically restarted when the chip temperature falls below 135 °C.
- Status feedback: in the case of an overtemperature fault condition, a Status Feedback is provided through the Input pin. The internal protection circuit disconnects the input from the gate and connects it instead to ground via an equivalent resistance of 100 Ω. The failure can be detected by monitoring the voltage at the Input pin, which will be close to ground potential.

Additional features of this device are ESD protection according to the Human Body model and the ability to be driven from a TTL Logic circuit (with a small increase in Rbs(on)).

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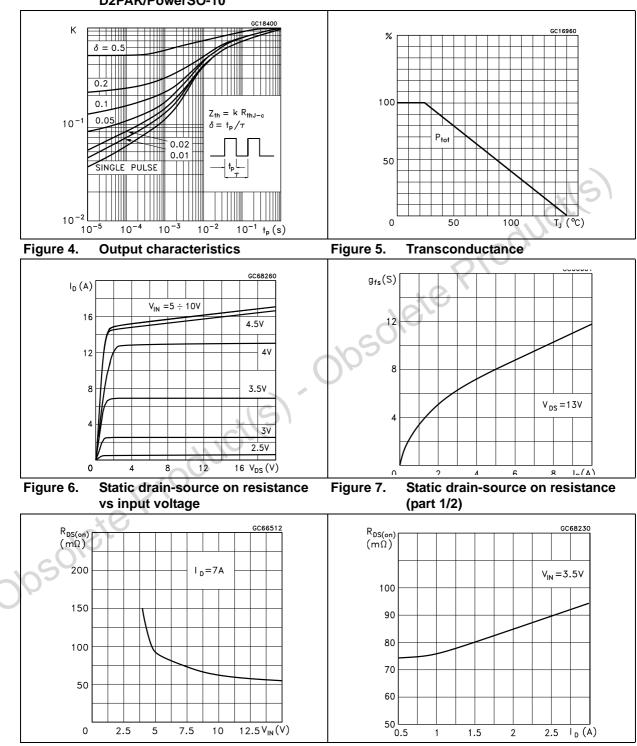
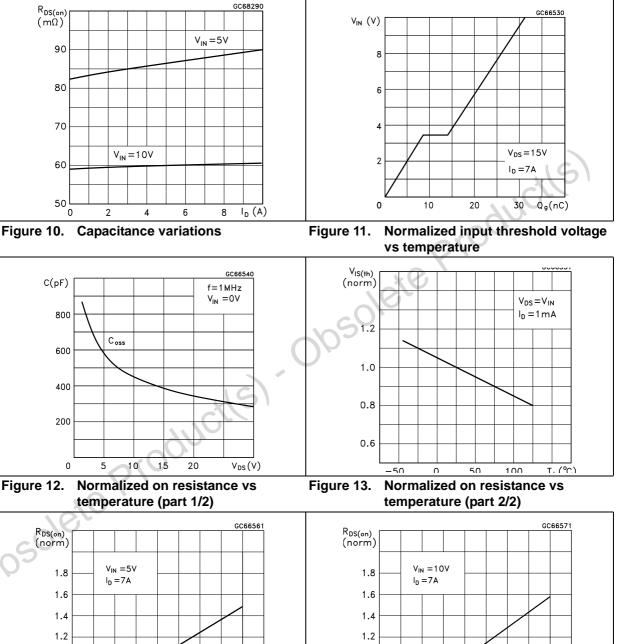


Figure 2. Thermal impedance for D2PAK/PowerSO-10

Figure 3. Derating curve

Figure 8. (part 2/2)



1.0

0.8

0.6

0.4

-50

0

50

100 T_J (℃)

Static drain-source on resistance Figure 9.



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1.0

0.8

0.6

0.4

-50

0

50

100 T_J (℃)

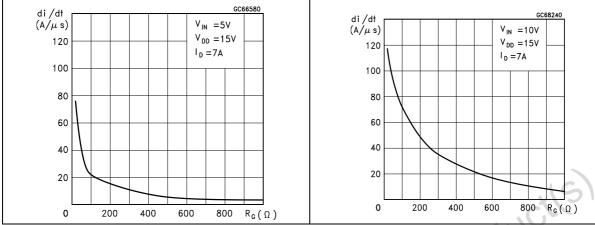


Figure 14. Turn-on current slope(part 1/2)

Figure 15. Turn-on current slope (part 2/2)

Figure 16. Turn-off drain-source voltage slope Figure 17. Turn-off drain-source voltage slope (part 1/2) (part 2/2)

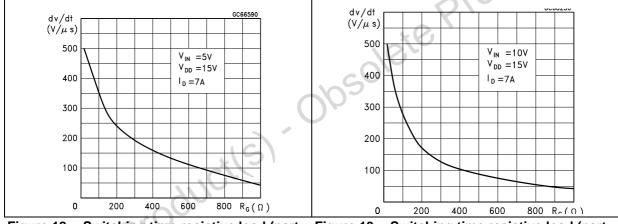
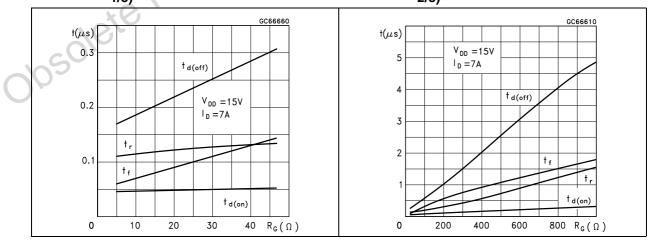


Figure 18. Switching time resistive load (part Figure 19. 1/3)

Switching time resistive load (part 2/3)

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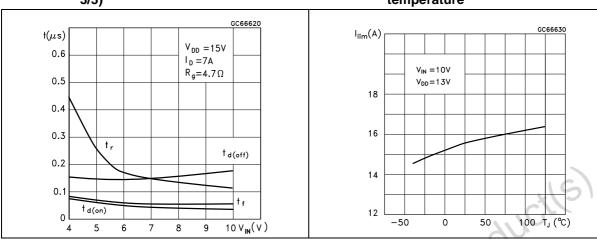
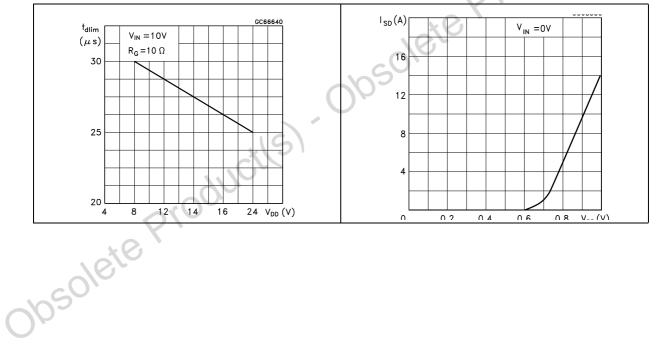


Figure 20. Switching time resistive load (part Figure 21. Current limit vs junction 3/3) temperature

Figure 22. Step response current limit

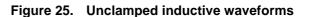
Figure 23. Source drain diode forward characteristics





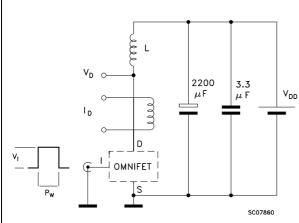
V_{CLAMP}

Figure 24. Unclamped inductive load test circuits



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IAR



V_{DD} V_{DD} Sco7872

Figure 27. Input charge test circuit

Figure 26. Switching times test circuits for resistive load



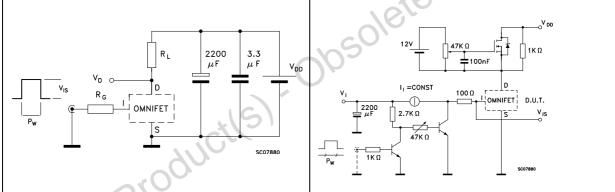
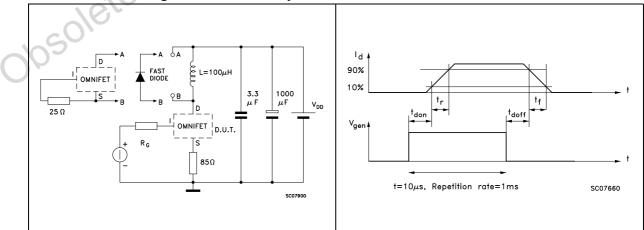


Figure 28. Test circuit for inductive load Figure 29. Waveforms switching and diode recovery times





4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: <u>www.st.com</u>.

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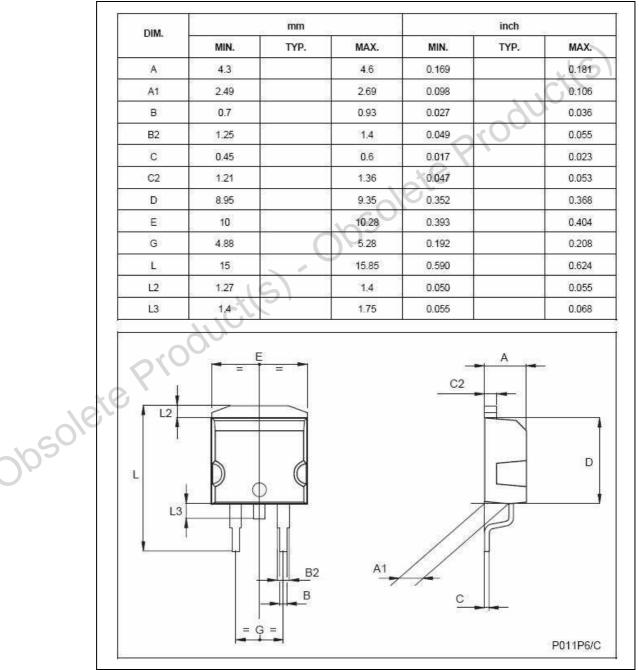
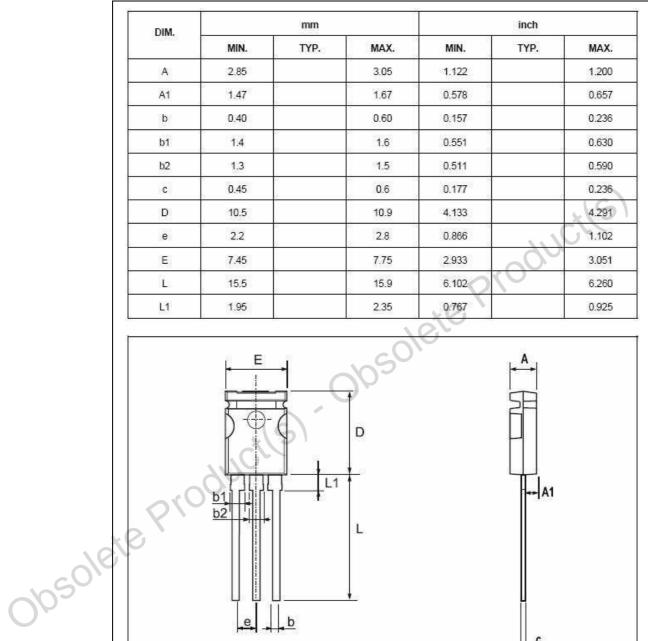


Figure 30. TO-263 (D2PAK) mechanical data





b

Figure 31. SOT82-FM mechanical data





C

P032R

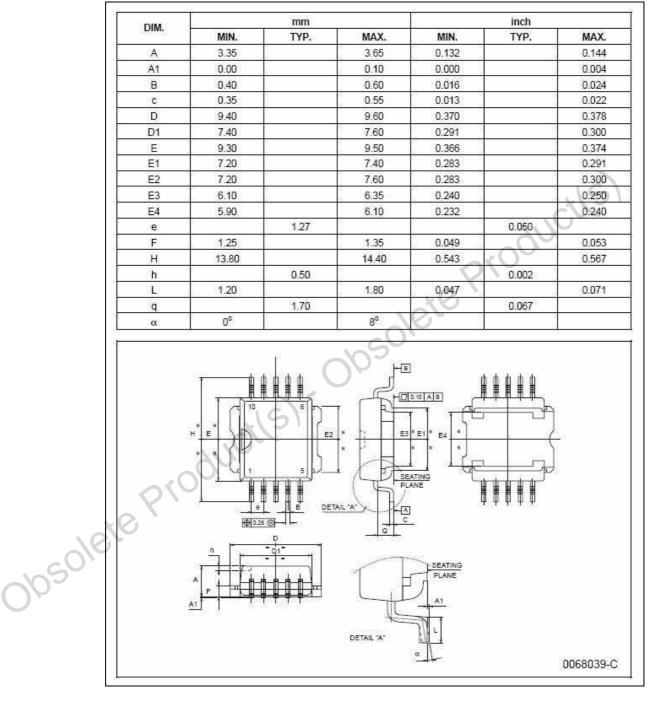


Figure 32. PowerSO-10 mechanical data



5 Revision history

Table 5.Document revision history

	Date	Revision	Changes			
	20-Jan-1998	1	Initial release.			
	21-Jun-2004	5	Update.			
	08-Apr-2009	6	Document reformatted. Added Table 1: Device summary on page 1. Updated Section 4: Package information on page 13			
	25-Sep-2013	7	Updated Disclaimer.			
25-Sep-2013 7 Updated Disclaimer.						



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